

CMOS 4-Bit Magnitude Comparator

High Voltage Types (20-Volt Rating)

■ CD4063B is a 4-bit magnitude comparator designed for use in computer and logic applications that require the comparison of two 4-bit words. This logic circuit determines whether one 4-bit word (Binary or BCD) is "less than", "equal to", or "greater than" a second 4-bit word.

The CD4063B has eight comparing inputs (A3, B3, through A0, B0), three outputs (A < B, A = B, A > B) and three cascading inputs (A < B, A = B, A > B) that permit systems designers to expand the comparator function to 8, 12, 16 . . . 4N bits. When a single CD4063B is used, the cascading inputs are connected as follows: (A < B) = low, (A = B) = high, (A > B) = low.

For words longer than 4 bits, CD4063B devices may be cascaded by connecting the outputs of the less-significant comparator to the corresponding cascading inputs of the more-significant comparator. Cascading inputs (A < B, A = B, and A > B) on the least significant comparator are connected to a low, a high, and a low level, respectively.

The CD4063B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shrink small-outline packages (PW and PWR suffixes). This device is pin-compatible with the standard 7485 TTL type.

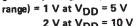
Features:

- Expansion to 8, 12, 16....4N bits by cascading units
- Medium-speed operation:

compares two 4-bit words in 250 ns (typ.) at 10 V

100% tested for quiescent current at 20 V

- Standardized symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Maximum input current of 1 μA at 18 V over full package temperature range; 100 nA at 18 V and 25°C
- Noise margin (full package temperature range)



$$2.5 V \text{ at } V_{DD} = 15 V$$

 Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

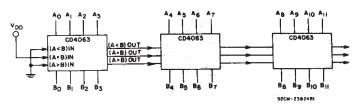
Applications:

Servo motor controls Process controllers

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (VDD)
Voltages referenced to VSS Terminal)0.5V to +20
INPUT VOLTAGE RANGE, ALL INPUTS
DC INPUT CURRENT, ANY ONE INPUT
POWER DISSIPATION PER PACKAGE (PD):
For T _A = -55°C to +100°C
For T _A = +100°C to +125°CDerate Linearity at 12mW/°C to 200m
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T _A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)
OPERATING-TEMPERATURE RANGE (T _A)
STORAGE TEMPERATURE RANGE (Tstg)65°C to +150°
LEAD TEMPERATURE (DURING SOLDERING);

At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max +265°C

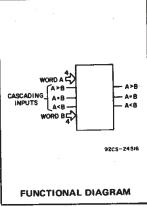


to TOTAL " TO (COMPARE) + 2.4 to (CASCADE), AT VDD = 10V (3 STAGES)

= 250 + (2 x 200) = 650 ns (TYP.)

Fig. 1 — Typical speed characteristics of a 12-bit comparator.

CD4063B Types



B3 (10 (1) (A <b)<sub>1N 2 (1) (A=B)_{1N} 3 (4 (A>B)_{1N} 4 (3) (A>B)_{0UT} 5 (2) (A=B)_{0UT} 6 (1)</b)<sub>	4 B2 3 A2					
(A<8)OUT 7 10	A0					
V _{SS}						

TERMINAL ASSIGNMENT

RECOMMENDED OPERATING CONDITIONS For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

	LIÅ	AI TS	
CHARACTERISTIC	Min.	Max.	UNITS
Supply-Voltage Range (For T _A =Full Package- Temperature Range)	3	18	v

STATIC ELECTRICAL CHARACTERISTICS

CHARACTER- ISTIC	CONE		VS	LIMI	TS AT I	NDICAT	ED TEN	APERA	UNITS		
ISTIC	Vo	VIN	VDD						+25		
	(V)	(V)	(V)	55	-40	+85	+125	Min.	Тур.	Max.	
Quiescent Device	· –	0,5	5	5	5	150	150	_	0.04	5	
Current, IDD Max.	_	0,10	10	10	10	300	300	-	0.04	10	
		0,15	15	20	20	600	600	-	0.04	20	μA
	. —	0,20	20	100	100	3000	3000	-	0.08	100	1
Output Low	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	-	
(Sink) Current	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6		mA
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	-	
Output High (Source) Current, 10H Min.	4.6	0,5	5	-0,64	-0.61	-0.42	-0.36	-0.51	-1	-	
	2,5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2		
	. 9,5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Output Voltage:	-	0,5	5		0	.05		-	0	0.05	
Low-Level, VOL Max.		0,10	10		0	.05			0	0.05	
AOF MAY	-	0,15	15		0	.05		_	0	0.05	v
Output Voltage:	-	0,5	5		4	.95		4.95	5	-	l v
High-Level,	_	0,10	10		9	.95		9.95	10		
VOH Min.	-	0,15	15		14	.95		14,95	15	_	
Input Low	0.5, 4.5	-	5		1	.5			_	1.5	
Voltage,	1, 9	_	10			3			—		
VIL Max.	1.5,13.5	_	15			4		_	-	4	
Input High	0.5, 4.5	_	5		3	1.5		3.5	—	—	v
Voltage,	1, 9	-	10			7		7	_	_	
VIH Min.	1.5,13.5	-	15		1	1		11	-	-	
Input Current IIN Max.		0,18	18	±0.1	±0.1	±1	±1	_	±10-5	±0.1	μA

COMMERCIAL CMOS	HIGH VOLTAGE ICs

TRUTH TABLE				

	100 B 100 B			KUTH TA						
		1	NPUTS							
	COMPA	RING		(C	ASCADIN	₩G		OUTPUTS		
A3, B3	A2, B2	A1, B1	A0, B0	A <b< th=""><th>A = B</th><th>A>B</th><th>A < B</th><th>A = B</th><th>A > B</th></b<>	A = B	A>B	A < B	A = B	A > B	
A3 > B3	oline X	X	X	X	X	X	0	0	1	
A3 = B3	A2 > B2	X	X .	x	· x .	x	0	0	1	
A3 = 83	A2 = B2	A1>B1	X 2	X	X	x	[.] 0	0	1	
A3 = B3	A2 = B2	A1 = B1	A0 > B0	X	x	x	0	0	1	
A3 = B3	A2 = B2	A1 = B1	A0 = B0	0	0	1	0	0	1	
A3 = B3	A2 = 82	A1 = B1	A0 = B0	- 0	1	i o	0	1	0	
A3 = B3	A2 = B2	A1 = B1	A0 = 80	¹ 1	0	0	1	0	0	
A3 = B3	A2 = B2	A1 = B1	A0 < B0	X	X	X	1	0	0	
A3 = B3	A2 = B2	A1 < B1	X	X	x	X	1	0	0	
A3 = B3	A2 < B2	x :	х	x	5 X 5 4	x	1	0	0	
A3 < B3	х	x	x	X	i x	X -	. 1	0	o	

X = Don't Care

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Logic 1 ≡ High Level

 $Logic 0 \equiv Low \ Level$

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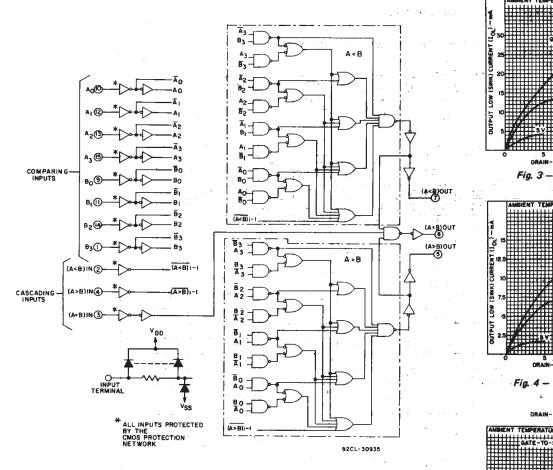
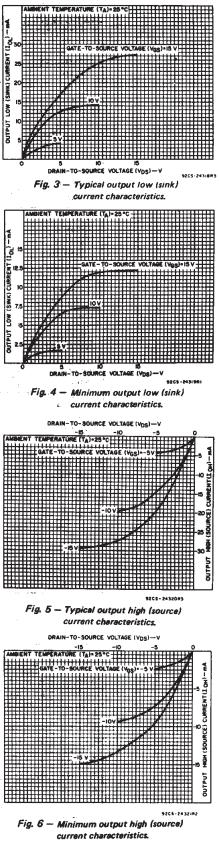


Fig. 2 - Logic diagram for CD4063B.

DYNAMIC ELECTRICAL CHARACTERISTICS

At $T_A = 25^{\circ}C$; Input t_r , $t_f = 20 \text{ ns}$, $C_L = 50 \text{ pF}$, $R_L = 200 \text{k}\Omega$

	TEST CONDI	TIONS	inster Lii		
CHARACTERISTIC	an a	V _{DD} Volts	Тур.	Max.	UNITS
Propagation Delay Time:		5	625	1250	
Comparing Inputs to		10	250	500	
Outputs, tPHL, tPLH		15	175	350	ns
		5	500	1000	113
Cascading Inputs to	. · · ·	10	200	400	
Outputs, tpHL, tpLH		15	140	280	арананан саранан саран Саранан саранан
		5	100	200	
Transition Time,		10	50	100	ns
^t THL ^{, t} TLH · · · ·		. 15	40	80	
Input Capacitance, CIN	Any Input		5	7.5	рF



CD4063B Types

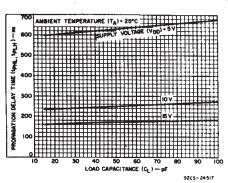


Fig. 7 – Typical propagation delay time vs. load capacitance ("comparing inputs" to outputs).

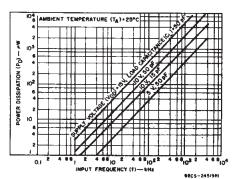


Fig. 10 – Typical power dissipation vs. frequency (see Fig. 12 – dynamic power dissipation test circuit).

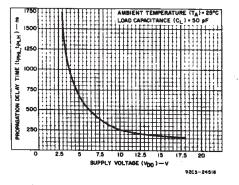


Fig. 8 – Typical propagation delay time vs. supply voltage ("comparing inputs" to outputs).

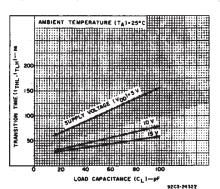
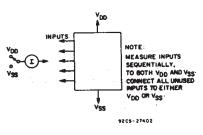
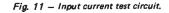


Fig. 9 - Typical transition time vs. load capacitance.





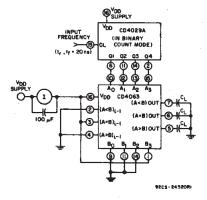


Fig. 12 - Dynamic power dissipation test circuit.

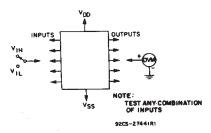
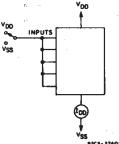
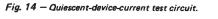
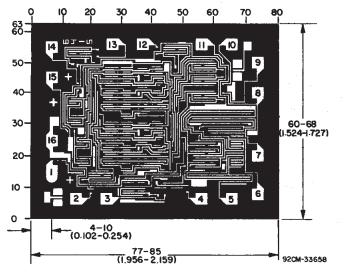


Fig. 13 - Input-voltage test circuit.



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Dimensions and pad layout for CD4063BH.

Dimensions in parantheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils $(10^{-3}$ inch).

COMMERCIAL CMOS HIGH VOLTAGE ICs

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD4063BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4063BEE4	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4063BF	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
CD4063BF3A	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
CD4063BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4063BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4063BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4063BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4063BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4063BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4063BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4063BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4063BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4063BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4063BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4063BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is



PACKAGE OPTION ADDENDUM

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J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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